

SMART

LITE

HV

Reliability Test System For Smart Power, Analog, WBG Devices



RETE: STATE OF THE ART APPROACH TO QUALIFY CHIPS FOR ZERO DEFECT & 100% YIELD

CUSTOMER BENEFIT	DEVICE
<ul style="list-style-type: none"> • Zero Defect & Zero Scraps • Shorter Time to Market • COO minimization • UNIVERSAL Test Platform • Industry 4.0 readiness • Competitivy • Sustainability 	<ul style="list-style-type: none"> • SOC • Multi die systems • MEMS • Memory • Smart Power ICs • Power SiC & GaN, • Photonics IC

POWER FROM 0W TO MORE THAN 1000W

VOLTAGE FROM 0V TO 6000V

TEMPERATURE FROM -40°C TO +175°C

● Universal Testing Platform.

● Tfr tester to combine stress and test in the same insertion.

● Configurable by HW kits and SW libraries to manage different IC families: low/high power SOC, Memories, MEMS, smART Power...

● Management of External Test/stress Instruments (on Fixture BOST IPs) to extend test and stress capabilities for the specific IC family.

● Scalable to approach engineering, Reliability and Production tests with the same platform, development and test environment.



- Universal Reliability Test System for Smart Power Devices suitable for Automotive market
- Stress like final application emulating the real loads, via the optional External Load Platform
- Per DUT high current PS channel
- Automotive Grade-0 compliancy - Temperature: -40°C to 175°C
- Thermal Chamber with Air Cooling Technology. High Temperature Uniformity: $\pm 3^{\circ}\text{C}$ at full load.
- Power Temperature Cycling according to JESD22-A105C

HTOL, PTC, LTOL, HTRB, ELFR, TDBI - Trials

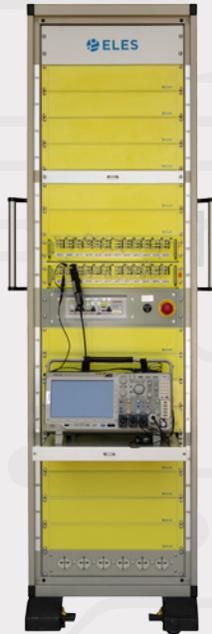
SMART LITE



- Universal Reliability Test System for Smart Power Devices suitable for Automotive market
- Stress like final application emulating the real loads, via the optional External Load Platform
- Per DUT high current PS channel
- Automotive Grade-0 compliancy – Temperature: -40°C to 150°C
- Thermal Chamber with Air Cooling Technology. High Temperature Uniformity: $\pm 3^{\circ}\text{C}$ at full load.

HTOL, LTOL, HTRB, ELFR, TDBI - Trials

EXTERNAL LOAD PLATFORM FOR smART e smART Lite



- Each smART & smART-Lite Fixture is provided of #192 pin contacts, 3A each, to connect each DUT to High Power loads outside the oven on External Load Platform
- Real load emulation like motors, solenoids, bulbs, lamps ...
- External Load Platform (ELP) characteristics:
 - Rack 19", 42 units
 - 16 independent Load Boards
 - Air temperature control system
 - Max P_{diss} = 32KW (2KW each Load Board)
- Probing Interface to measure voltage, current and waveform of each load

smART HV



- All smART system features embedded (No external power load connection).
- Up to 6KV for WBG devices effective stress
- Per DUT High Voltage PS channel
- Effective stress of Galvanic Insulation between Low Voltage and High Voltage Domains

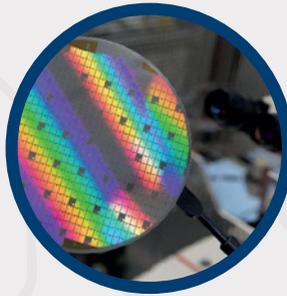
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UNIQUE SELLING PROPOSITION

**state-of-the-art test
and reliability flow, that ensures:**



**Early Detection of issues
in the Design Process**



**Shorten Time to Market
and CoO minimization**



**Zero defect and zero
scraps Production**

**... moving from a Pass-Fail
to Learn From Fail approach**

FIXTURES

FIXTURES FOR Q&R AND MANUFACTURING ENVIRONMENT



smART | smART Lite



smART HV



LOAD BOARD

- Consolidated design rules and qualified building blocks to optimize Fixtures performances and reliability.
- Qualified components libraries and application of consolidated Design for Manufacturing rules.
- BoST IPs to Maximize test and stress coverage, including high accuracy parametric measurement for an effective Test for Reliability (TfR) flow.
- Fixture Robustness optimized for extreme conditions and continuous handling.
- Signal and Power Integrity simulation / optimization service to guarantee and optimize electrical performance versus test application specs.
- Thermal Simulation to Guarantee Stress Temperature accuracy at extreme conditions.